

SOT1401-1

wafer level chip-scale package, 25 balls; 2.51 mm x 2.51 mm
x 0.5 mm body

1 September 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP25
Package type industry code	WLCSP25
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	5-10-2015
Manufacturer package code	SOT1401

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.48	-	2.51	2.54	mm
E	package width	2.48	-	2.51	2.54	mm
A	seated height	0.46	-	0.5	-	mm
A ₂	package height	0.275	-	0.3	0.325	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	25	-	



2. Package outline

WLCSP25: wafer level chip-scale package, 25 balls; 2.51 x 2.51 x 0.5 mm SOT1401-1

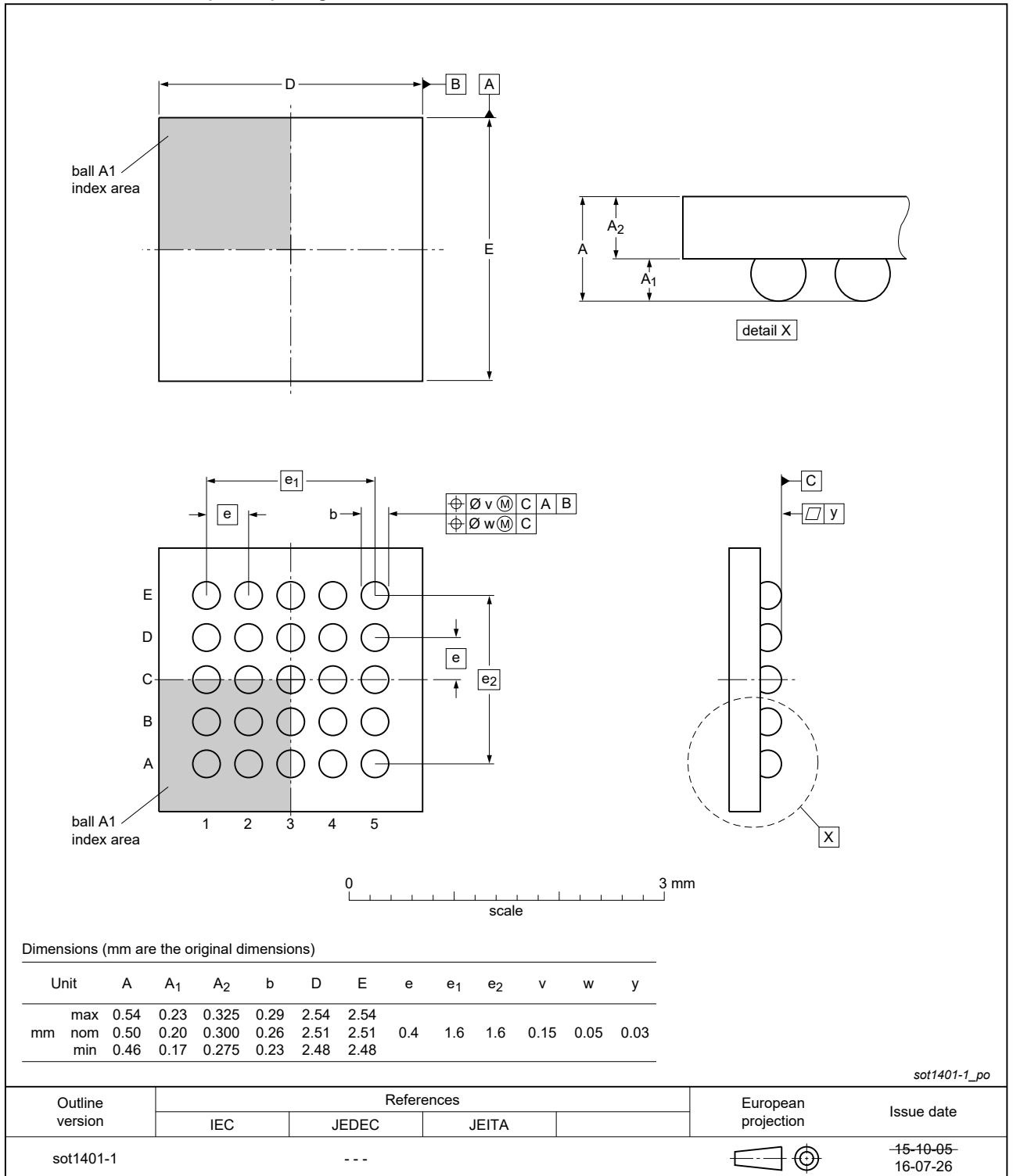


Fig. 1. Package outline WLCSP25 (SOT1401-1)

3. Legal information

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